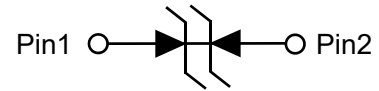


## Description

The PESDKC2FD5VB protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. They feature large cross-sectional area junctions for conducting high transient currents, offer desirable electrical characteristics for board level protection, such as fast response time, low operating voltage. It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



**Circuit Diagram**

## Feature

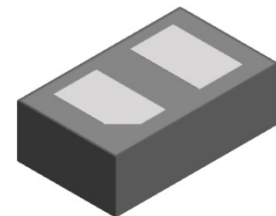
- 80W peak pulse power per line ( $t_p = 8/20\mu s$ )
- DFN1006-2L package
- Response time is typically  $< 1\text{ ns}$
- Bidirectional configurations
- High ESD protection
- Low clamping voltage
- RoHS compliant
- Transient protection for data lines to  
IEC 61000-4-2(ESD)  $\pm 25\text{kV}$ (air),  $25\text{kV}$ (contact);  
IEC 61000-4-5 (Lightning)  $8\text{A}$  ( $8/20\mu s$ )



**Marking (Top View)**

## Applications

- Smart Phone and Tablet PC
- TV and Set Top Box
- Wearable Devices
- PDA



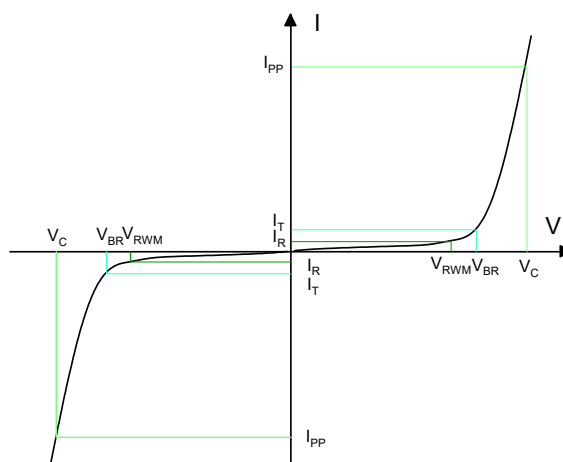
**DFN1006-2L(Bottom View)**

## Mechanical Characteristics

- Lead finish: 100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:  $260^{\circ}\text{C}$
- Pure tin plating:  $7 \sim 17\text{ }\mu\text{m}$

## Electronics Parameter

Symbol	Parameter
$V_{RWM}$	Peak Reverse Working Voltage
$I_R$	Reverse Leakage Current @ $V_{RWM}$
$V_{BR}$	Breakdown Voltage @ $I_T$
$I_T$	Test Current
$I_{PP}$	Maximum Reverse Peak Pulse Current
$V_C$	Clamping Voltage @ $I_{PP}$
$P_{PP}$	Peak Pulse Power
$C_J$	Junction Capacitance
$I_F$	Forward Current
$V_F$	Forward Voltage @ $I_F$



## Electrical characteristics per line@25°C (unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Peak Reverse Working Voltage	$V_{RWM}$	-	-	-	5	V
Breakdown Voltage	$V_{BR}$	$I_t = 1\text{mA}$	5.6	-	8.4	V
Reverse Leakage Current	$I_R$	$V_{RWM} = 5\text{V}$	-	-	1	$\mu\text{A}$
Clamping Voltage	$V_C$	$I_{PP} = 8\text{A}, t_p = 8/20\mu\text{s}$	-	-	10	V
Junction Capacitance	$C_J$	$V_R = 0\text{V}, f = 1\text{MHz}$	-	15	18	pF

## Absolute maximum rating@25°C

Rating	Symbol	Value	Units
Peak Pulse Power ( $t_p = 8/20\mu\text{s}$ )	$P_{PP}$	80	W
Peak Pulse Current ( $t_p = 8/20\mu\text{s}$ )	$I_{PP}$	8	A
Lead Soldering Temperature	$T_L$	260 (10 sec)	°C
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55~+150	°C

## Typical Characteristics

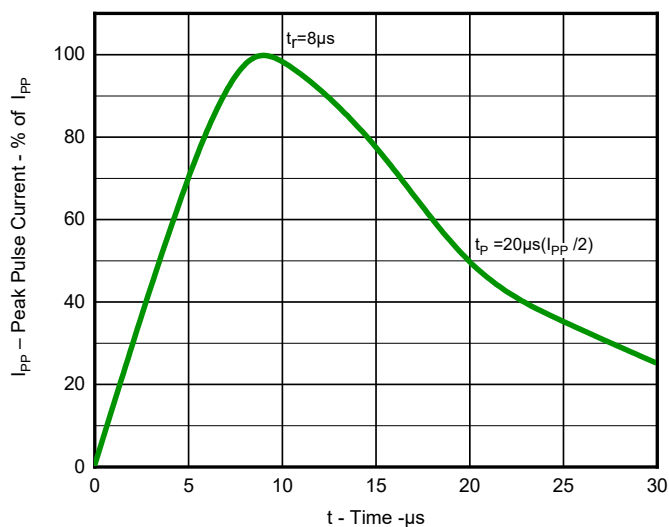
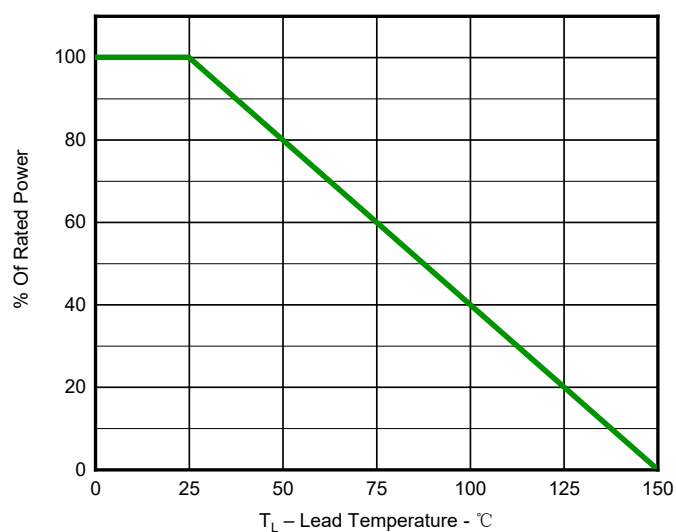
Fig 1. Pulse Waveform(8/20 $\mu s$ )

Fig 2. Power Derating Curve

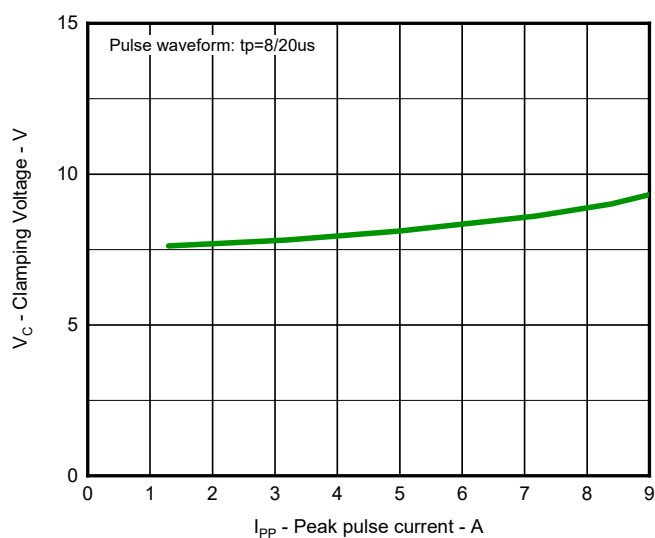


Fig 3. Clamping voltage vs. Peak pulse current

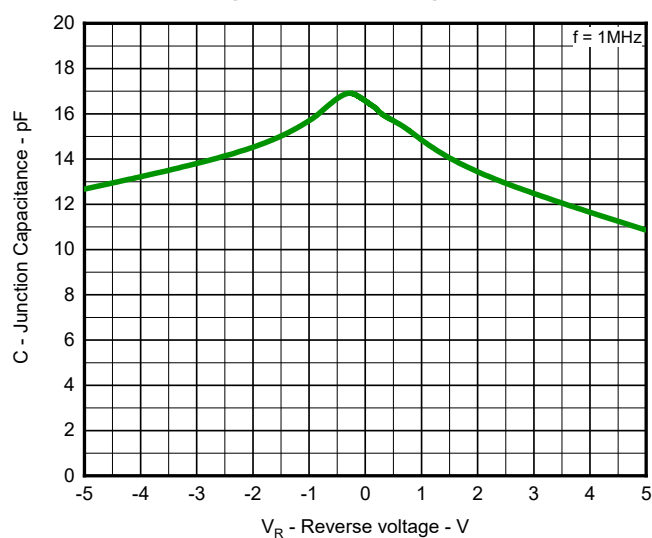


Fig 4. Capacitance vs. Reverse voltage

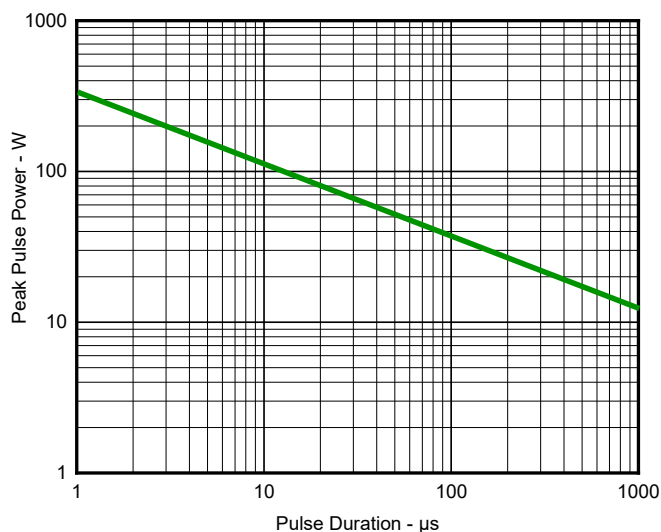


Fig 5. Non Repetitive Peak Pulse Power vs. Pulse time

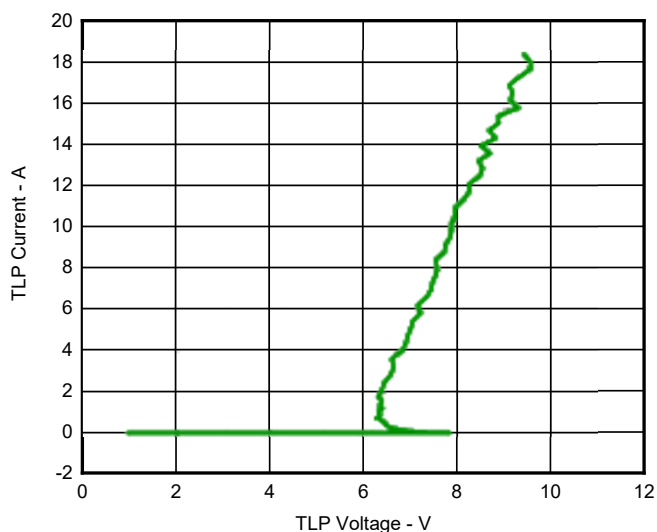
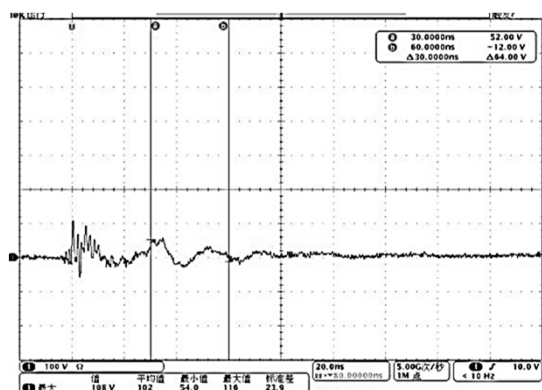
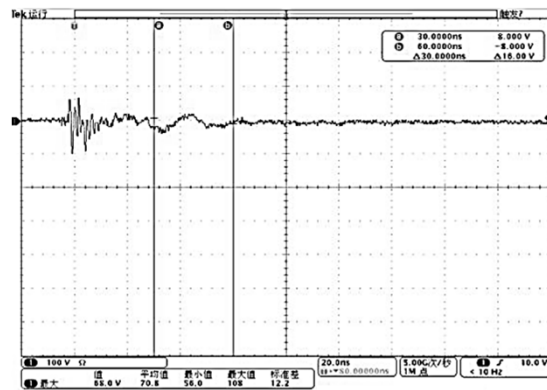


Fig 6. TLP Measurement

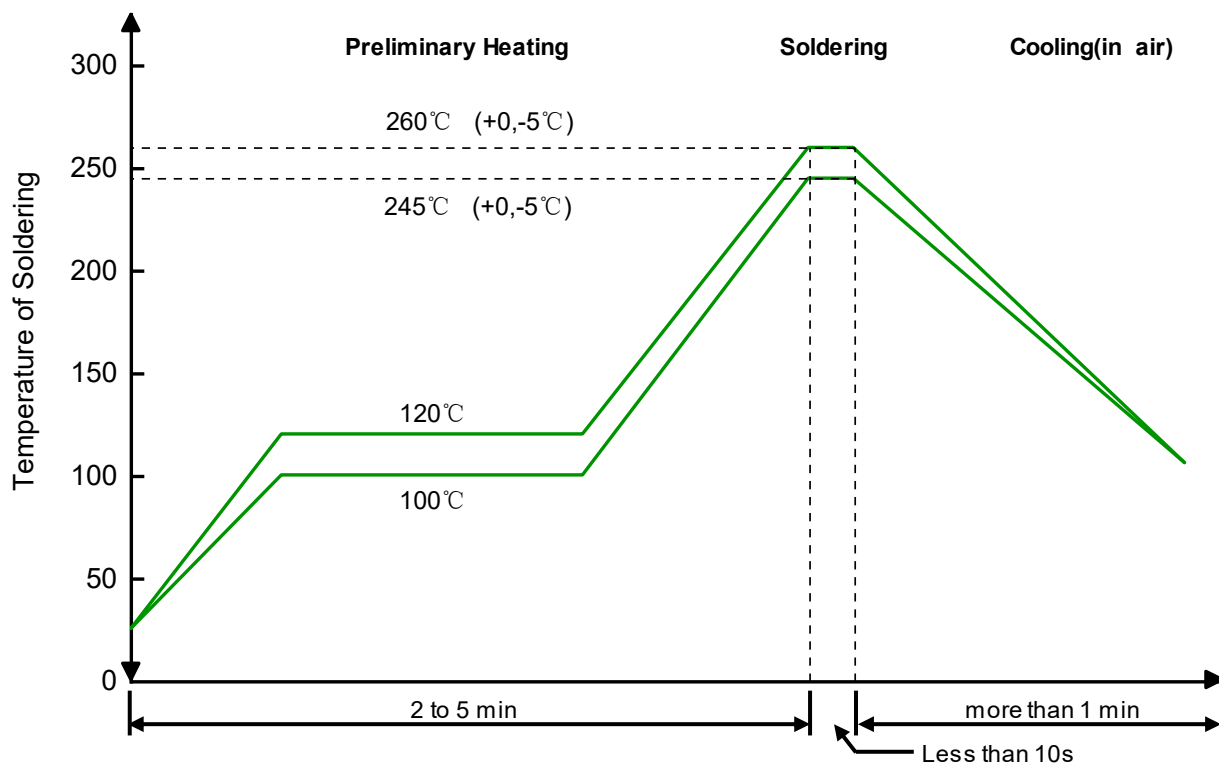


**Fig 7. Clamping Voltage at IEC61000-4-2  
+8kV Pulse Waveform**



**Fig 8. Clamping Voltage at IEC61000-4-2  
-8kV Pulse Waveform**

## Solder Reflow Recommendation



Remark: Pb free for 260°C; Pb for 245°C.

## PCB Design

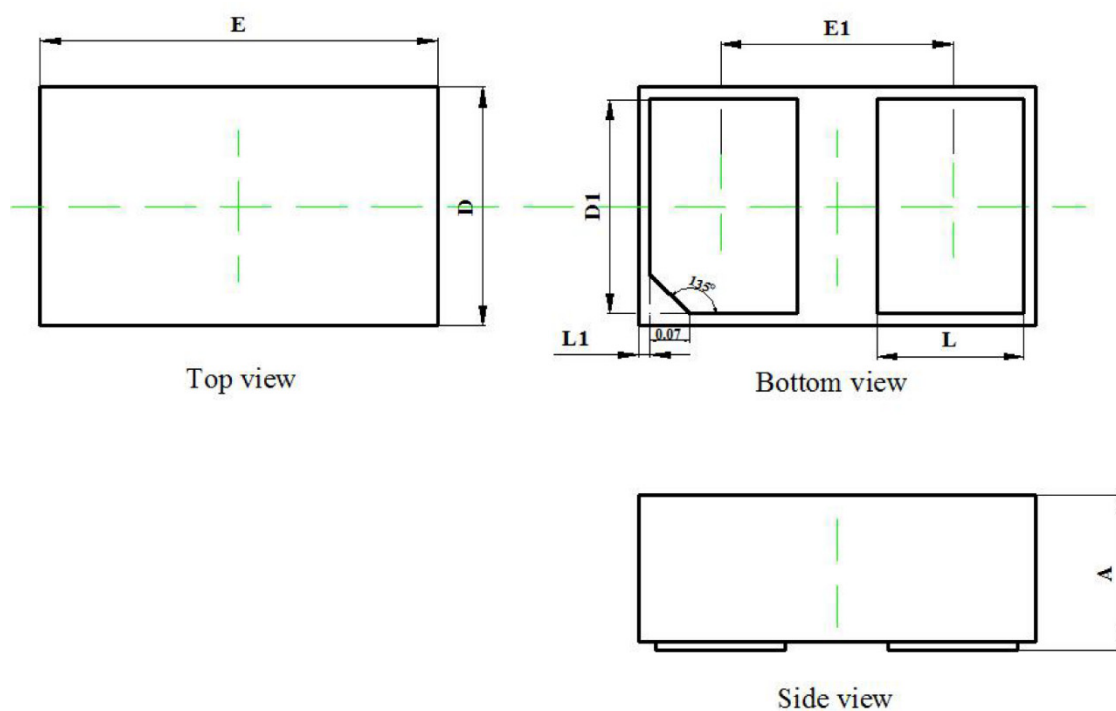
For TVS diodes a low-ohmic and low-inductive path to chassis earth is absolutely mandatory in order to achieve good ESD protection. Novices in the area of ESD protection should take following suggestions to heart:

- Do not use stubs, but place the cathode of the TVS diode directly on the signal trace.
- Do not make false economies and save copper for the ground connection.
- Place via holes to ground as close as possible to the anode of the TVS diode.
- Use as many via holes as possible for the ground connection.
- Keep the length of via holes in mind! The longer the more inductance they will have.

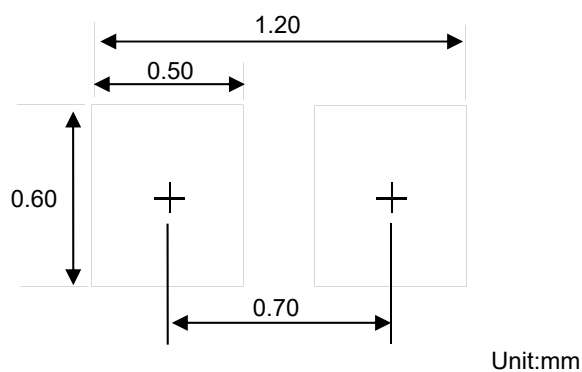
## Ordering information

Device	Package	Reel	Shipping
PESDKC2FD5VB	DFN1006-2L (Pb-Free)	7"	10000 / Tape & Reel

## Product dimension (DFN1006-2L)




Dim	Millimeters		Inches	
	Min	Max	Min	Max
A	0.32	0.55	0.013	0.022
D	0.55	0.65	0.022	0.026
E	0.90	1.10	0.035	0.043
D1	0.35	0.55	0.014	0.022
E1	0.55	0.65	0.022	0.026
L	0.15	0.38	0.006	0.015
L1	0.00	0.10	0.000	0.004



Suggested PCB Layout


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